

soldering systems eliminate costly cuits & heat seal connectors.

THE HSM 'SMARTHERM' HEAT SEALING SYSTEM

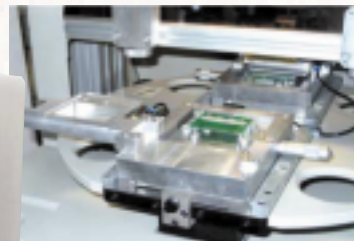
- Pneumatic bonding head provides up to 1,175N force
- Rotary table design permits fast cycle time
- Digital control and floating thermode ensure consistent pressure and heat transfer
- Temperature range 50° to 400°C
- High quality heat seal application up to 0.25mm pitch or less.

SmarTherm is a fast-throughput microprocessor-controlled machine indispensable for producing flexible connections between components, such as HSC-to-LCD, HSC-to-PCB or TAB-to-HSC and other applications. The system requires no profiling capability since few variables govern its operation. Heat-sealing temperatures, maintained to an accuracy of $\pm 1^\circ\text{C}$, are merely pre-set from 50° to 400°C, and dwell times are also selectable in increments of 0 to 5, 0 to 12 and 0 to 30 seconds.

The bonding cycle, triggered by a real time pressure sensor, occurs as the floating thermode ensures consistent pressure while heat transfer takes place along the flexfoil to LCD and/or PCB. Precision holding fixtures are available for a wide range of applications with optional hold-downs, vacuum and micrometers when required to maintain alignment. Available as an option is a B&W or color camera system for finer pitch magnification.



Digital pressure control is throughout entire production cycle.



Rotary work feeder for fast load/unload. Operated manually or pneumatic power as option.

Efficient and cost-effective heat sealing with SmarTherm. Shown with optional vision system.

SmarTherm Applications



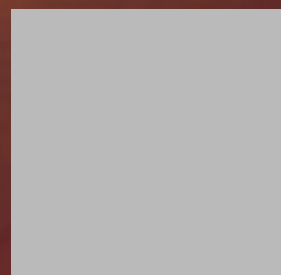
LCD-HSC-TAB-PCB Connection



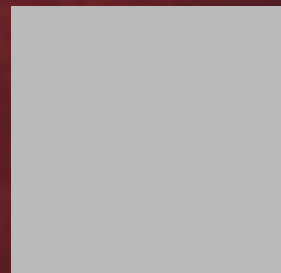
LCD-HSC-PCB Connection



LCD-HSC-TAB Connection



LCD-HFGFDHC-TAGFDB Connection



LCDGDFHGFHAB Connection